



SOT766-1

plastic thermal enhanced low profile quad flat package; 176 leads; body 24 mm x 24 mm x 1.4 mm; exposed die pad

1 June 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP176
Package type industry code	HLQFP176
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	13-6-2002
Manufacturer package code	SOT766

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		23.9	24	24.1	mm
package width		23.9	24	24.1	mm
seated height		-	-	1.6	mm
package height		1.35	1.4	1.45	mm
nominal pitch		-	0.5	-	mm
actual quantity of termination		-	176	-	A/A



2. Package outline

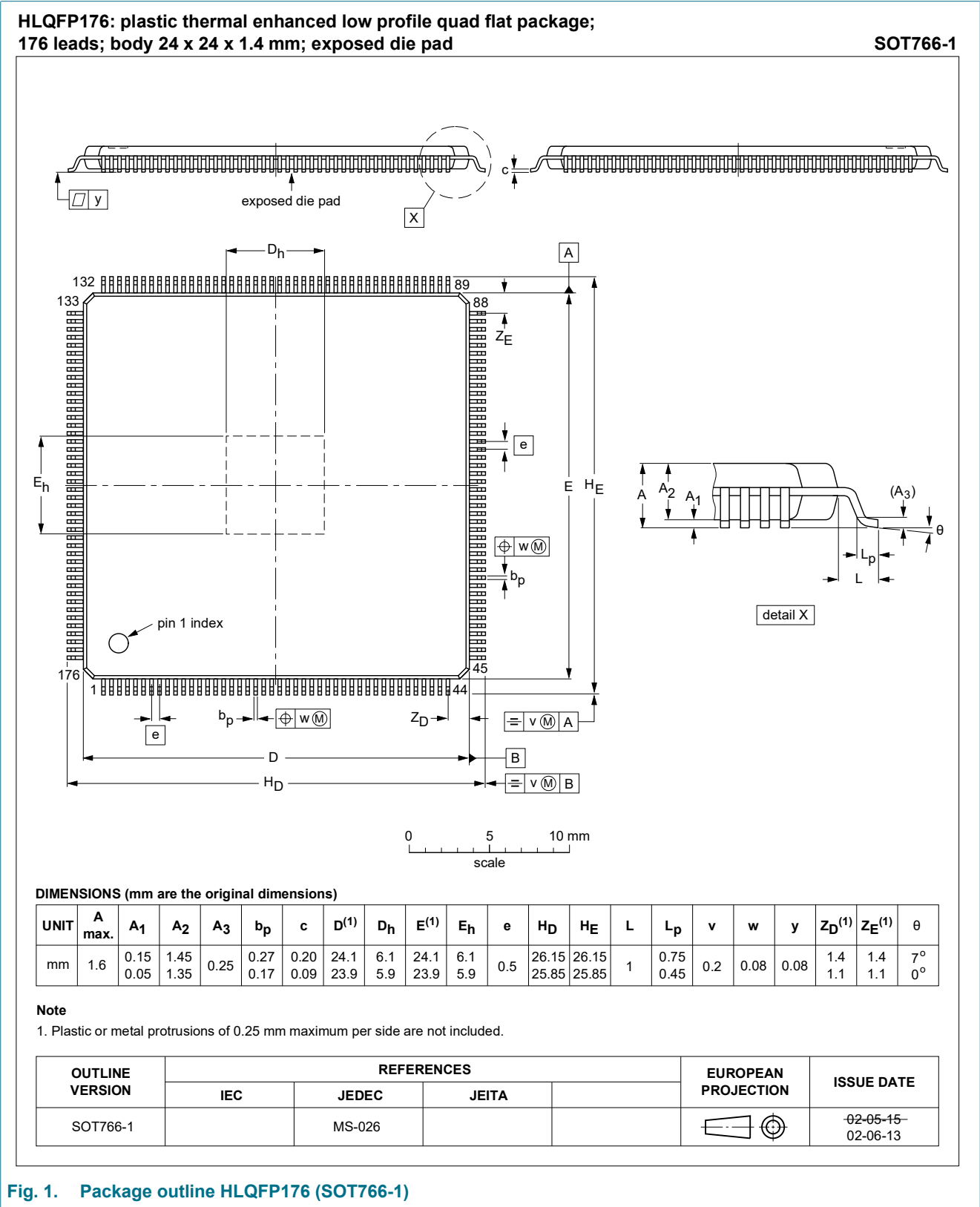


Fig. 1. Package outline HLQFP176 (SOT766-1)

3. Soldering

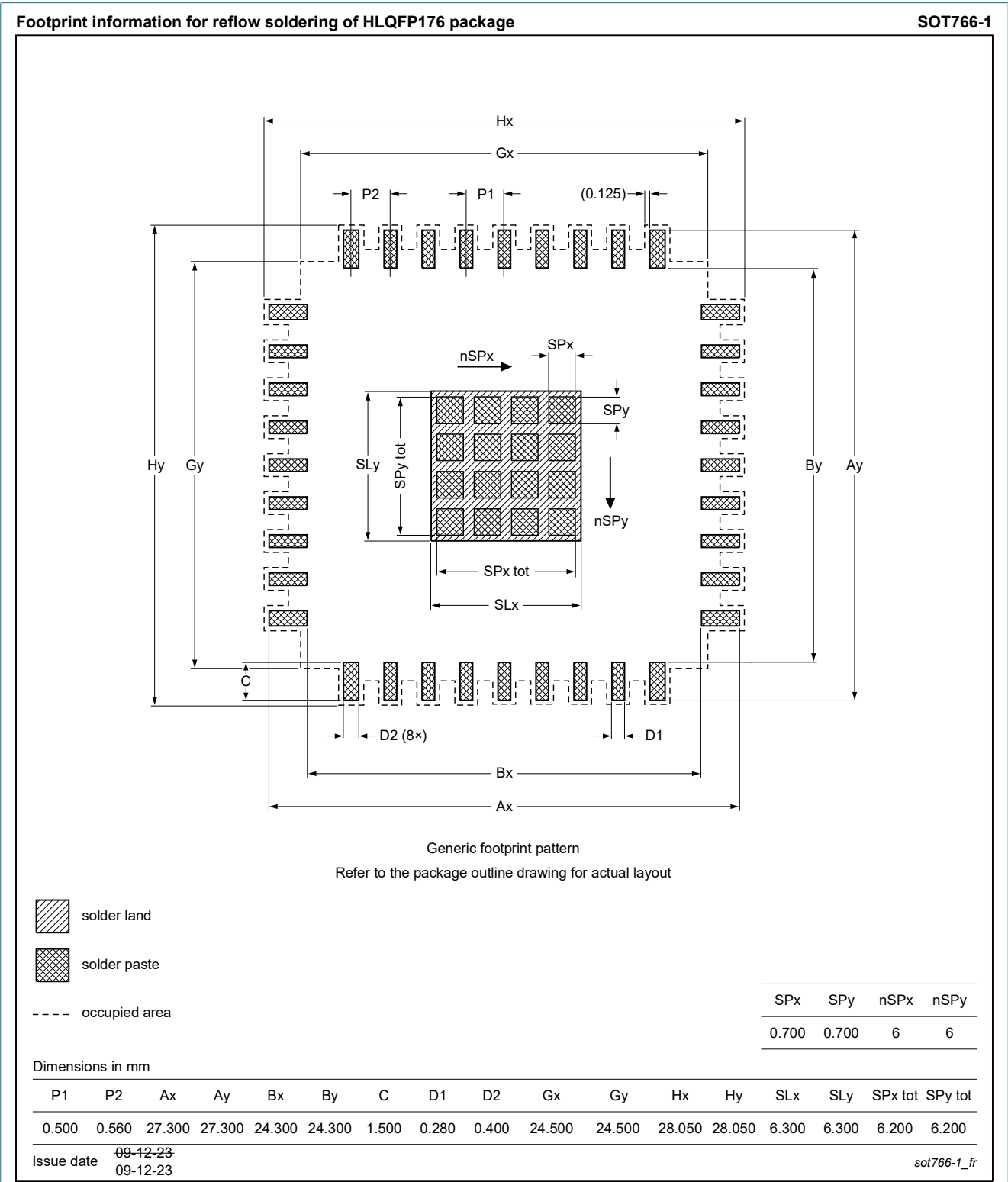


Fig. 2. Reflow soldering footprint for HLQFP176 (SOT766-1)

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4. Legal information

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Date of release: 1 June 2018